

zCase: AMKOR-007C2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Thomas P. Glenn)	Group No.:	Unknown
)		
Serial No.:	Unknown)		
)		
Filed:	Herewith)	Examiner:	Unknown
)		
For:	Plastic Integrated Circuit Package and)		
	Method and Leadframe for Making the)		
	Package)		

PRELIMINARY AMENDMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir/Madam:

Prior to the initial examination of the above-identified continuation patent application, please amend the application as follows:

In the Specification:

On page 1, please insert the following section after the Title and before the section captioned Field of Invention:

RELATED APPLICATIONS

The present application is a continuation of U.S. Application Serial No. 10/171,702 entitled PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE filed June 14, 2002, which is a continuation of U.S. Application Serial No. 09/615,107 entitled PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE filed July 13, 2000, which is a continuation of U.S. Application Serial No. 09/103,760 entitled PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE filed June 24, 1998 and issued as U.S. Patent No. 6,143,981 on November 7, 2000.